



Product Change Notification

Change Notification #: 116016 - 00
Change Title: Intel® Server Chassis R2312WTXXX and Intel® Server System R2312WTTYSR, PCN 116016-00, Product Design, Removal of EFI Clips from Chassis Wall.
Date of Publication: January 04, 2018

Key Characteristics of the Change:

Product Design

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material: *	January 19, 2018
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* Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.

Description of Change to the Customer:

Intel is implementing the following changes on the Intel® Server Chassis R2312WTXXX and Intel® Server System R2312WTTYSR:

- Removal of EMI Clips from chassis walls to avoid interference with the 12 x 3.5" hot swap backplane as shown in the images below.

Image 1. Before Change - Chassis with EMI clips



Image 2. After change - Chassis without EMI clips



Image 3. Before change - Chassis with EMI clips

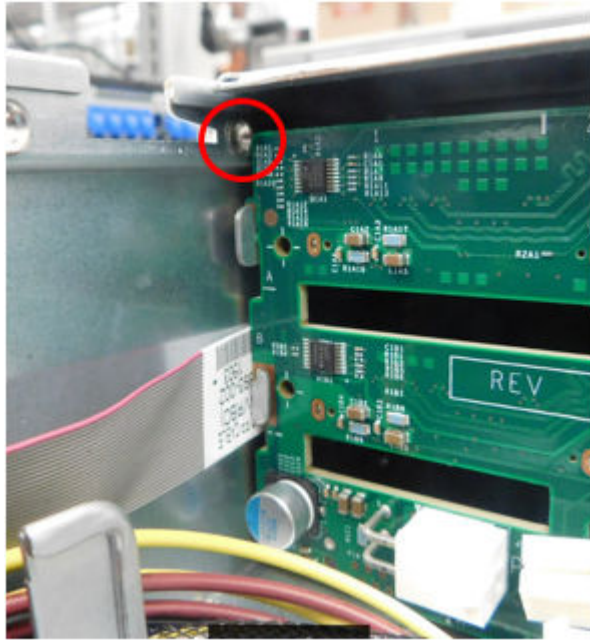
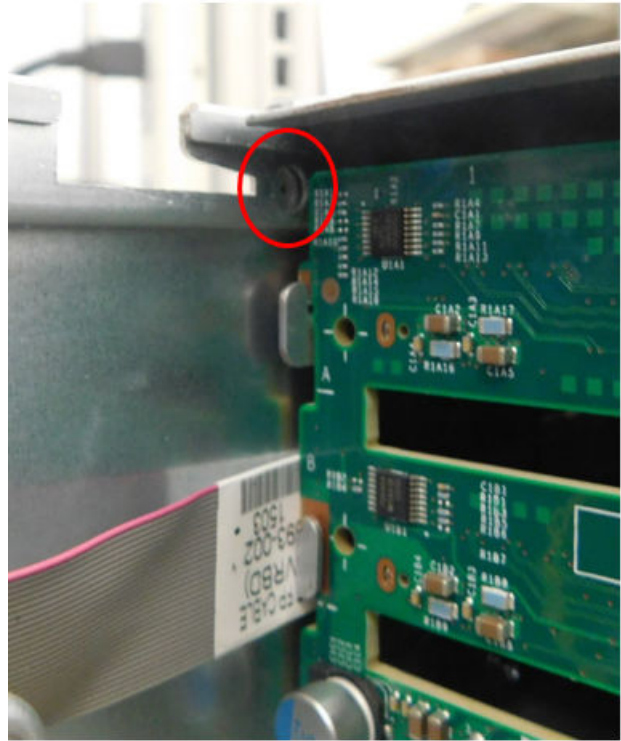


Image 4. After change - Chassis without EMI clips



Customer Impact of Change and Recommended Action:

Intel does not expect any impact to customers from these changes, but encourages customers to understand the changes and determine the impact on their applications.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change TA	Post Change TA
R2312WTTYSR	951229	J11495-011	J11495-012
R2312WTXXX	951230	H46998-005	H46998-006

PCN Revision History:

Date of Revision:

January 4, 2018

Revision Number:

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Reason:

Originally Published PCN



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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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